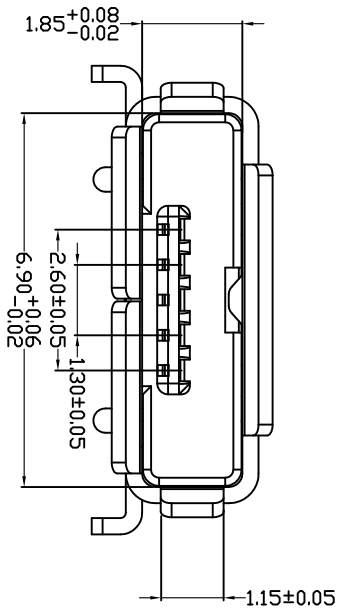
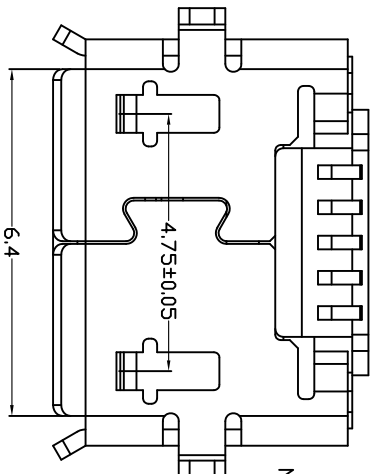
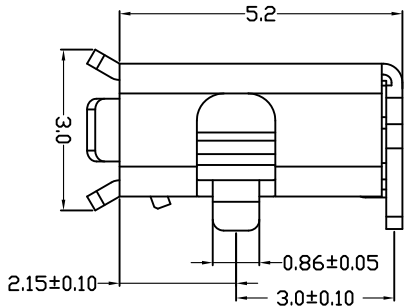
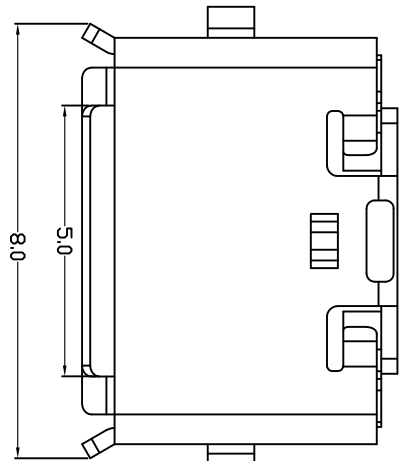


PCB LAYOUT



- Note:
1. Material:
 - 1.1 Housing: High temperature thermoplastic with 9.1UL94v-0
 - 1.2 Contact: copper alloy t=0.15mm
 - 1.3 Shell: copper alloyϕSUS
 2. Specification:
 - 2.1 Current rating: 1 A Max.
 - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 - 2.3 Contact resistance: 30 m Ω Max.
 - 2.4 Insulation resistance: 100 M Ω Min.
 - 2.5 Total mating force: 3.57 Kgf Max.
 - 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
 - 2.7 Temperature range: -30C~80C

銳創科技有限公司
FRONTEK TECHNOLOGY CO., LTD.

TOLERANCE: XX ±0.30 XXX ±0.20 XXXX ±0.15 X* ±0.2 X*X* ±0.05		DRAWN BY : ANDY		DATE : 2016-02-24		PART NAME: MICRO USB AB Type DIP 0.6(8.35*4.45)	
UNITS: mm [inch]		CHECKED BY: FRANK		DATE : 2016-02-24		PART NO. TMC80-USB05-895	
SCALE: 1:1		APPROVED BY: DAVID		DATE : 2016-02-24		MOLD NO.	
SIZE: A4						DRAW NO.	
						SHEET NO.	